

Electronic Patent Application Fee Transmittal

Application Number:	10528153			
Filing Date:	19-Aug-2005			
Title of Invention:	Method of adhesion of conductive materials, laminate, and adhesive composition			
First Named Inventor/Applicant Name:	Hiroyuki Sakamoto			
Filer:	Burton A. Amernick/Pam Rollins-Butler			
Attorney Docket Number:	27604-00003US1			
Filed as Large Entity				
U.S. National Stage under 35 USC 371 Filing Fees				
Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Basic Filing:				
Pages:				
Claims:				
Miscellaneous-Filing:				
Petition:				
Patent-Appeals-and-Interference:				
Post-Allowance-and-Post-Issuance:				
Extension-of-Time:				

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Statutory disclaimer	1814	1	140	140
Total in USD (\$)				140